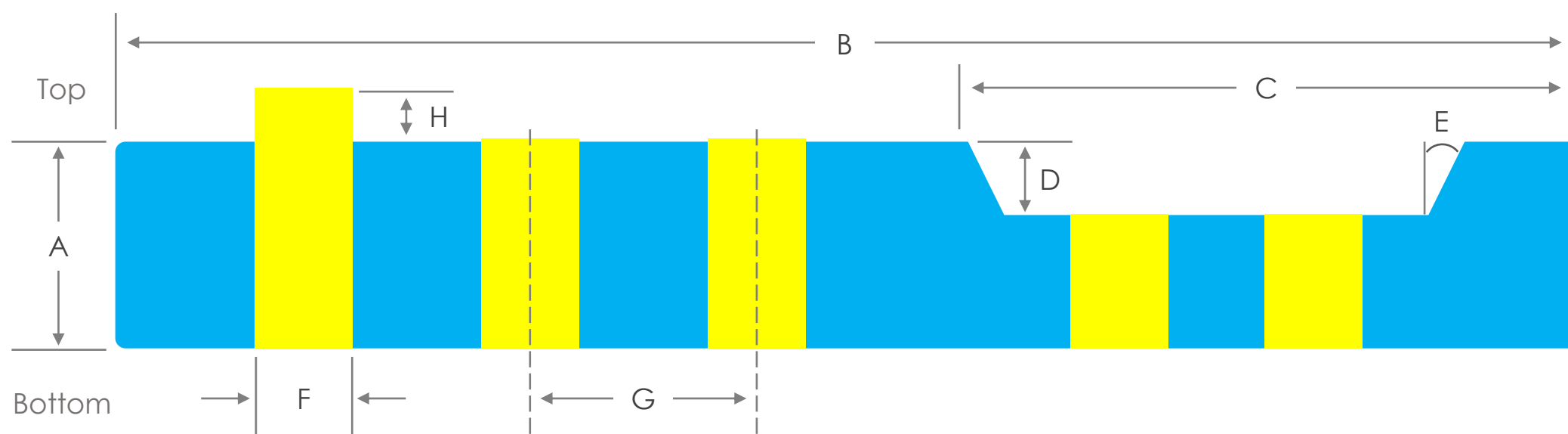


Product Information

Our proprietary glass forming and processing technology provides proprietary glass wafer microstructure solutions for the semiconductor, MEMS and biotechnology industries.

Application 3D Integration of MEMS Sensors & Semiconductor Devices
RF components and Modules, Automotive RF & Camera Modules
CMOS Image Sensors

Specifications Used for 2.5D / 3D Integration High accuracy and low tolerance
Wafer diameter from 2" to 12" Wafer thickness from 350 μm
Through holes Filled conductive vias



The panel sizes listed are for our standard production models, but can be customized to support unique specifications.

-	A	B	C	D	E	F	G	H
Spec	350 μm \uparrow ($\pm 20\mu\text{m}$)	~12 inch	$\Phi 500\mu\text{m}$ \uparrow	350 μm \uparrow	20 $^\circ$ \uparrow	200 μm \uparrow	750 μm \uparrow ($\pm 50\mu\text{m}$)	~30 μm
Electrode	Kovar, 42 Alloy, Tungsten							
Material	Borofloat 33							

We are proudly a member of IGCA